

**SEMICONDUCTOR PACKAGE**

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**ABSTRACT OF THE DISCLOSURE**

A semiconductor package is disclosed that bonds a semiconductor chip to a  
10 leadframe using a flip chip technology. An exemplary semiconductor package  
includes a semiconductor chip having a plurality of input-output pads at an active  
surface thereof. A plurality of leads are superimposed by the bond pads and active  
surface of the semiconductor chip. The leads have at least one exposed surface at a  
bottom surface of the package body. A plurality of conductive connecting means  
15 electrically connect the input-output pads of the chip to the leads. A package body  
is formed over the semiconductor chip and the conductive connecting means. The  
bottom surface portions of the leads are exposed to the outside.